



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-02-12
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	LDO7*0922BR6	A	BO2A	2014-02-12
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	<b>false</b>
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	<b>false</b>
Product(s) does not meet EU RoHS requirements and is not under exemptions	<b>false</b>
Product(s) is obsolete, no information is available	<b>false</b>
Product(s) is unknown, no information is available	<b>false</b>
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	LDO7*0922BR6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.357	mg	supplier	die	Silicon (Si)	7440-21-3		1.335	mg	983788	16688
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	3685	63
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1474	25
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.003	mg	2211	38
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.012	mg	8843	150
Leadframe	Copper & its alloys	38.495	mg	supplier	alloy	Copper (Cu)	7440-50-8		38.209	mg	992570	477613
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.018	mg	468	225
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.032	mg	831	400
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.236	mg	6131	2950
Die attach	Other Organic Materials	0.523	mg	supplier	glue	Silver (Ag)	7440-22-4		0.476	mg	910134	5950
Die attach				supplier	glue	acrylate	Proprietary		0.026	mg	49713	325
Die attach				supplier	glue	Methacrylate	Proprietary		0.021	mg	40153	263
Bonding wire	Other inorganic materials	0.054	mg	supplier	wire	Copper (Cu)	7440-50-8		0.054	mg	1000000	675
encapsulation	Other Organic Materials	38.028	mg	supplier	mold compound	Silica, vitreous	60676-86-0		33.351	mg	877012	416888
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		1.521	mg	39997	19013
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		1.521	mg	39997	19013
encapsulation				supplier	mold compound	phenol resin	Proprietary		1.141	mg	30004	14263
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.114	mg	2998	1425
encapsulation				supplier	mold compound	additive	Proprietary		0.38	mg	9993	4750
connections coating	Solder	1.543	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.543	mg	1000000	19288